

Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
VNH9045AQTR	B0DY*VH94AAC	A	CA2A	2025-03-17
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	150	mg	Each	ECOPACK® 3
Identity	Authority			
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information			
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles	
3	260	3	
Bulk solder termination	Terminal plating	Terminal base alloy	Comment
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0

Package designator	Package size	Number of instances	Shape
qfn	6x6	28	No lead
Comment	B0DY QFN 6X6 TRIPLE PAD L26+2		

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020		Response
1 - Product(s) meets EU ELV requirements without any exemptions		true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
Exemption Id.	Description	

QueryList : California Prop65 list, dated 3rd January 2025				Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen				false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen				true
Substance	amount in product (mg)	Application	ppm in product	
Nickel	0.028	alloy	187	

QueryList :Customer		Response
QUERY		Response

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014					Response
QUERY					Response
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products					false
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products					false
Hazardous substance					
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE	
O	O	O	O	O	

QueryList : REACH-21st January 2025					Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH					true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product	
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH					true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material	



QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Tin, Tungsten,

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	false

QueryList:Stockholm Convention Persistent Organic Pollutants (POP)	Response
Product is compliant with Annex A, B and C of Stockholm Convention Persistent Organic Pollutants	true

QueryList: EU Ship Recycling Regulation No. 1257/2013	Response
Product contains hazardous materials listed in Annex II of EU Ship Recycling Regulation No.1257/2013 and 2009/16/EC Directive	False

PFAS/PTFE Declaration	Response
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene,Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride	False

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	B0DY*VH94AAC		150.0000		7000000.0	1000001.0				
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or Dies or Wafer (choose)	M-011 Other inorganic materials	2.257	mg	supplier	die	Silicon(Si)	7440-21-3		1.879	mg	832521	12527				
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.076	mg	33673	507				
				supplier	metallisation	Copper(Cu)	7440-50-8		0.033	mg	14621	220				
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.028	mg	12406	187				
				supplier	metallisation	Silver(Ag)	7440-22-4		0.012	mg	5317	80				
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.010	mg	4431	67				
				supplier	metallisation	Tungsten(W)	7440-33-7		0.129	mg	57156	860				
				supplier	metallisation	Vanadium(V)	7440-62-2		0.002	mg	886	13				
				supplier	Passivation	Silicon nitride(Si3N4)	12033-89-5		0.012	mg	5317	80				
				supplier	passivation	Silicon oxide	7631-86-9		0.058	mg	25698	387				
				supplier	polymer coating	polyimide	proprietary		0.018	mg	7975	120				
				Leadframe	M-004 Copper and its alloys	43.038	mg	supplier	alloy	Copper(Cu)	7440-50-8		40.664	mg	944839	271093
								supplier	alloy	Iron (Fe)	7439-89-6		0.716	mg	16636	4773
supplier	alloy	Iron phosphide	26508-33-8						0.166	mg	3857	1107				
supplier	alloy	Zinc(Zn)	7440-66-6						0.053	mg	1231	353				
supplier	metallization	Silver(Ag)	7440-22-4						1.439	mg	33436	9593				
supplier	glue	Silver(Ag)	7440-22-4						0.686	mg	863980	4573				
Die attach	M-011 Other inorganic materials	0.794	mg	supplier	glue	phenolic Resin	9003-35-4		0.036	mg	45340	240				
				supplier	glue	Hexanediol diglycidyl ether	16096-31-4		0.036	mg	45340	240				
				supplier	glue	Bisphenol F type epoxy resin	9003-36-5		0.004	mg	5038	27				
				supplier	glue	Epoxy Cresol Novolac	29690-82-2		0.028	mg	35264	187				
				supplier	glue	Epoxyde bisphenol A	25068-38-6		0.004	mg	5038	27				
				supplier	wire	Copper(Cu)	7440-50-8		1.131	mg	1000000	7540				
Bonding wires	M-004 Copper and its alloys	1.131	mg	supplier	wire	Copper(Cu)	7440-50-8		0.212	mg	1000000	1413				
Bonding wires 2	M-004 Copper and its alloys	0.212	mg	supplier	wire	Copper(Cu)	7440-50-8		0.212	mg	1000000	1413				
Encapsulation	M-011 Other inorganic materials	100.988	mg	supplier	mold compound	Silica vitreous	60676-86-0		88.869	mg	879996	592460				
				supplier	mold compound	Biphenyl epoxy	85954-11-6		5.049	mg	49996	33660				
				supplier	mold compound	Phenolic resin	205830-20-2		3.939	mg	39005	26260				
				supplier	mold compound	Epoxy type resin	proprietary		2.020	mg	20002	13467				
				supplier	mold compound	Carbon black	1333-86-4		0.202	mg	2000	1347				
				supplier	mold compound	other	proprietary		0.909	mg	9001	6060				
Connections coating	Solder	1.580	mg	supplier	solder alloy	Tin(Sn)	7440-31-5		1.580	mg	1000000	10533				